

SOCKET APPARATUS

Abstract of the Disclosure

A socket having a structure which is suitable for electrical connection with ball-shaped lead terminals of an IC package is shown. When a cover (12) is pushed down, a latch (70) moves away, a slide plate (40) slides toward the positive side in an X direction through levers (52) and (50) and movable shaft (58) and both arms of each contact maker (30) open. Each lead terminal (solder ball) (32a) of the BGA package (32) is freely inserted between both arms of a respective contact maker (30) when in the open state. When cover (12) rises to its highest position, slide plate (40) slides in the reverse direction by the spring force of a compression coil spring, thereby returning to the its original position and both arms of each contact (32) engage each lead terminal (32a) in such a way as to hold it from opposite sides with a result that an electrical connection based on compressive engagement is obtained between each contact element (30) and each respective terminal (32a).

FIGURE 16